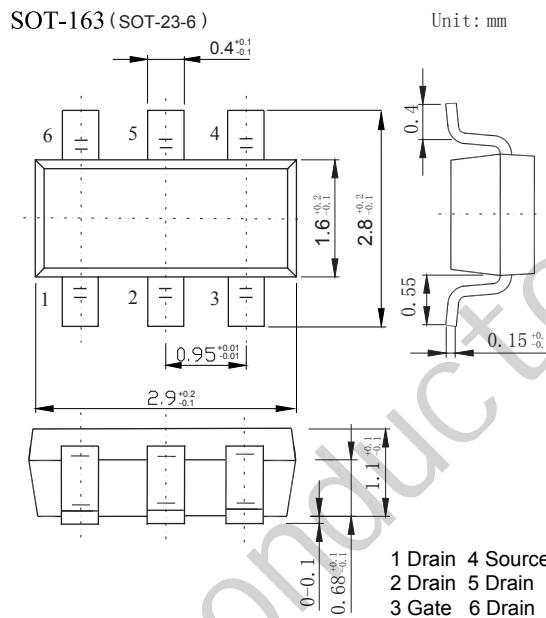
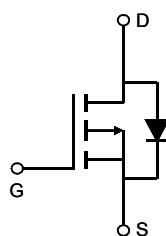


■ Features

- $V_{DS} (V) = -30V$
- $I_D = 5 A (V_{GS} = -10V)$
- $R_{DS(ON)} < 47m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} < 64m\Omega (V_{GS} = -4.5V)$
- $R_{DS(ON)} < 85m\Omega (V_{GS} = -2.5V)$



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	-5	A
		-4	
Pulsed Drain Current	I_{DM}	-28	
Power Dissipation	P_D	2	W
		1.3	
Thermal Resistance.Junction- to-Ambient	R_{thJA}	62.5	°C/W
		110	
Thermal Resistance.Junction- to-Lead	R_{thJL}	50	
Junction Temperature	T_J	150	°C
Junction Storage Temperature Range	T_{stg}	-55 to 150	

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$		-1		μA
		$V_{DS}=-30\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$		-5		
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$		± 100	nA	
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=-250 \mu\text{A}$	-0.5	-1.3		V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10\text{V}, I_D=-5\text{A}$		47		$\text{m}\Omega$
		$V_{GS}=-10\text{V}, I_D=-5\text{A}, T_J=125^\circ\text{C}$		74		
		$V_{GS}=-4.5\text{V}, I_D=-4\text{A}$		64		
		$V_{GS}=-2.5\text{V}, I_D=-1\text{A}$		85		
On state drain current	$I_{D(\text{ON})}$	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	-28			A
Forward Transconductance	g_{FS}	$V_{DS}=-5\text{V}, I_D=-5\text{A}$		18		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		645	780	pF
Output Capacitance	C_{oss}			80		
Reverse Transfer Capacitance	C_{rss}			55	80	
Gate resistance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	4		12	Ω
Total Gate Charge (10V)	Q_g	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-5\text{A}$		14	17	nC
Total Gate Charge (4.5V)				7	8.5	
Gate Source Charge	Q_{gs}			1.5		
Gate Drain Charge	Q_{gd}			2.5		
Turn-On Delay Time	$t_{d(\text{on})}$			6.5		
Turn-On Rise Time	t_r	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=3\Omega, R_{GEN}=3\Omega$		3.5		ns
Turn-Off Delay Time	$t_{d(\text{off})}$			41		
Turn-Off Fall Time	t_f			9		
Body Diode Reverse Recovery Time	t_{rr}			11	13.5	
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=-5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		3.5		nC
Maximum Body-Diode Continuous Current	I_s				-2.5	A
Diode Forward Voltage	V_{SD}	$I_s=-1\text{A}, V_{GS}=0\text{V}$			-1	V

* The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Typical Characteristics

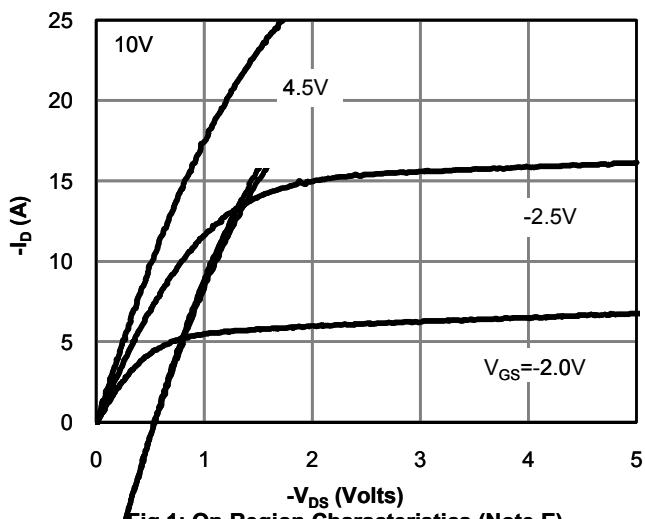


Fig 1: On-Region Characteristics (Note E)

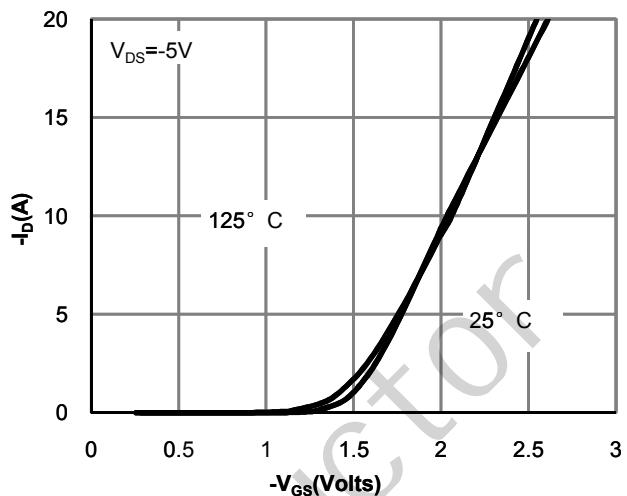


Figure 2: Transfer Characteristics (Note E)

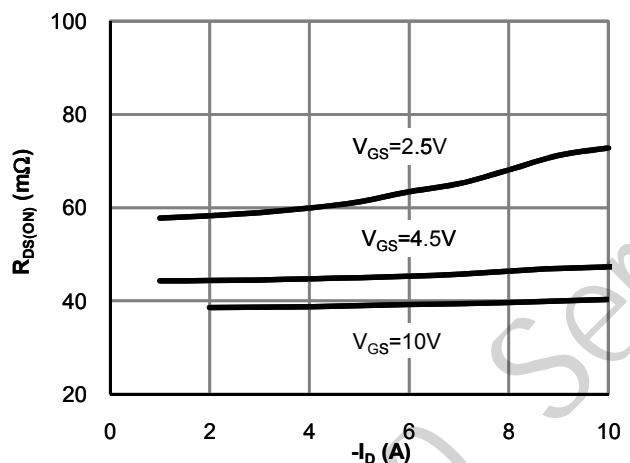


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

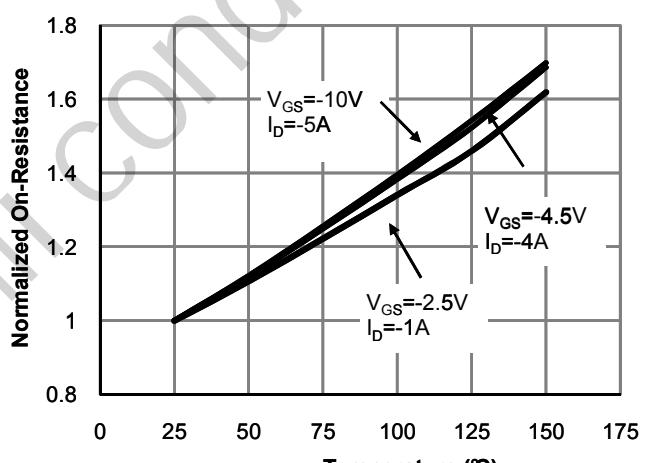


Figure 4: On-Resistance vs. Junction Temperature (Note E)

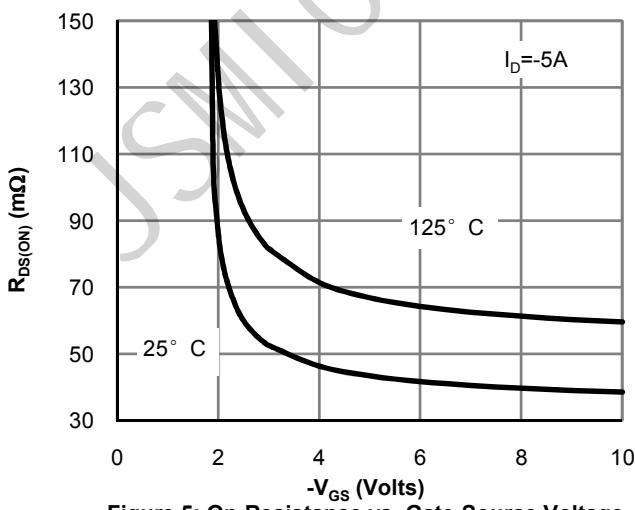


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

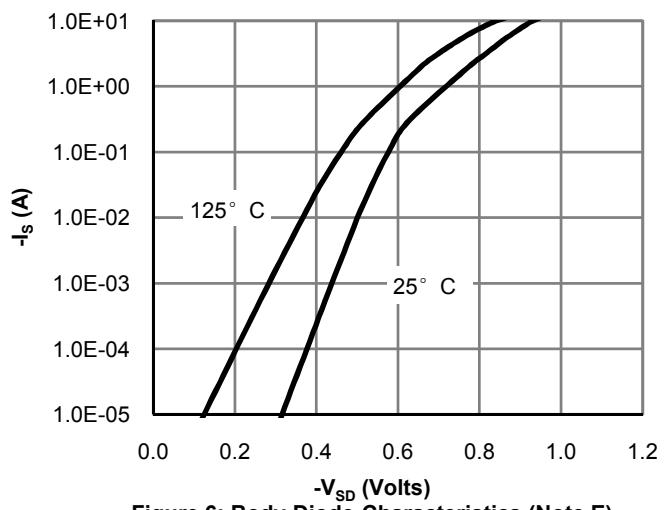


Figure 6: Body-Diode Characteristics (Note E)

■ Typical Characteristics

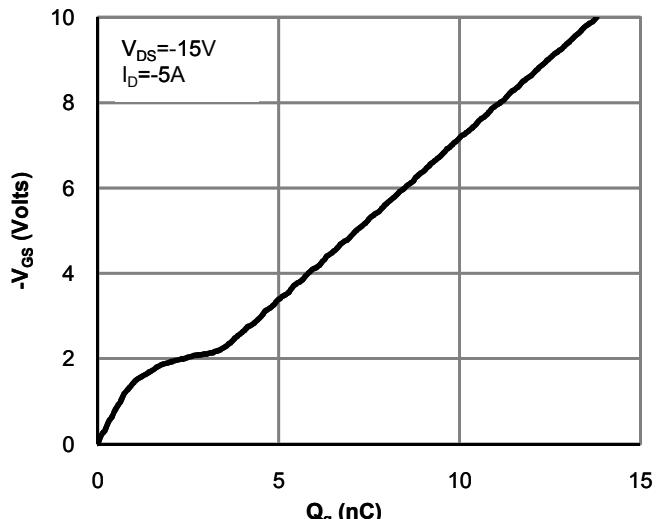


Figure 7: Gate-Charge Characteristics

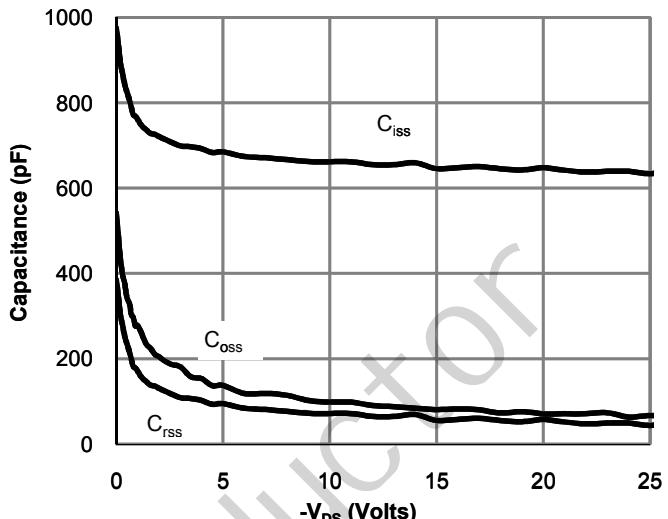


Figure 8: Capacitance Characteristics

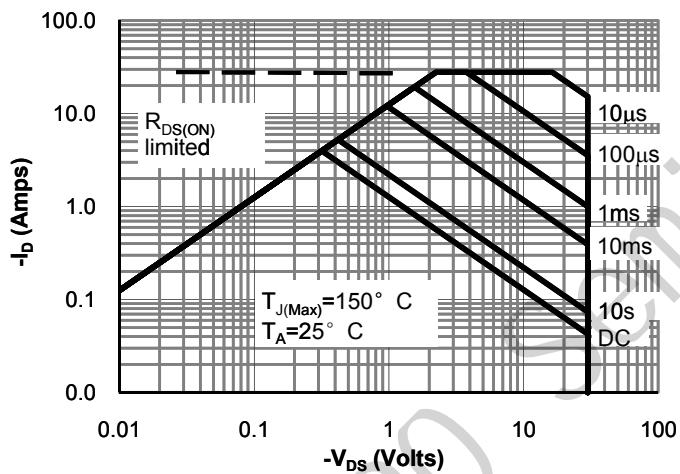


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

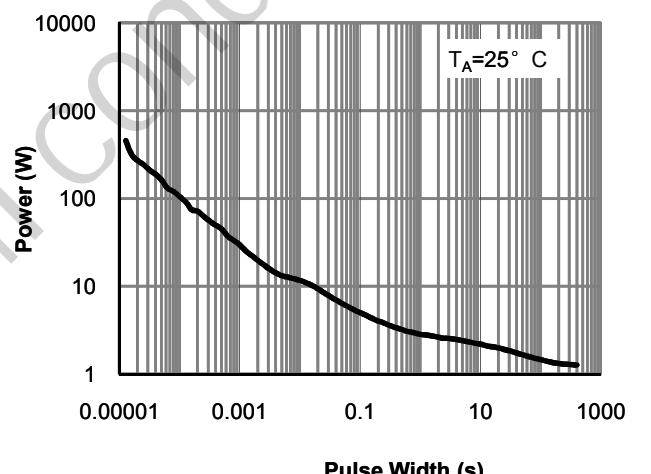


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

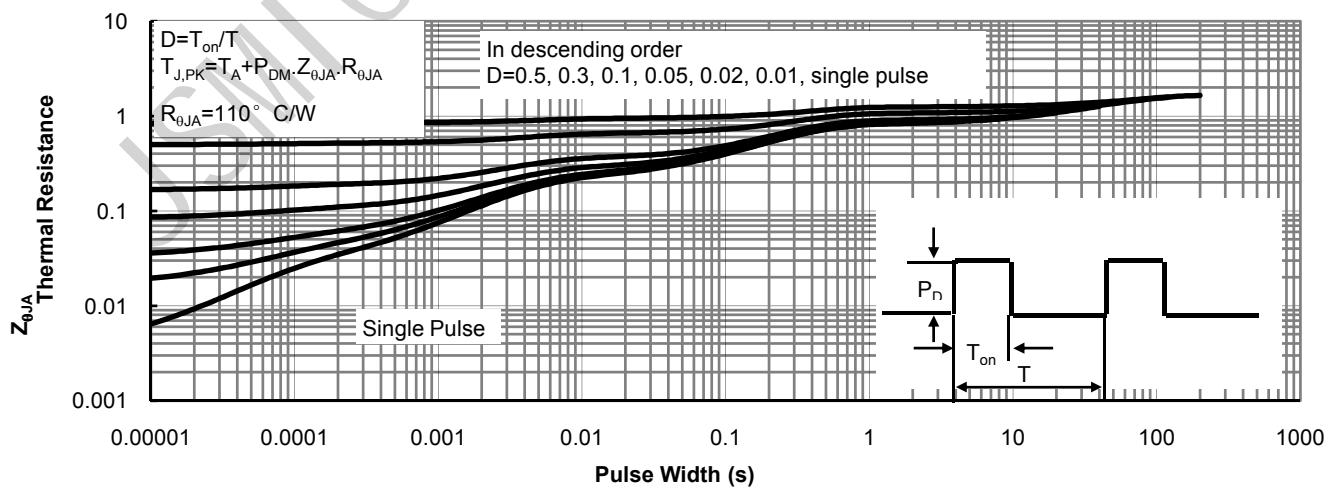


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)